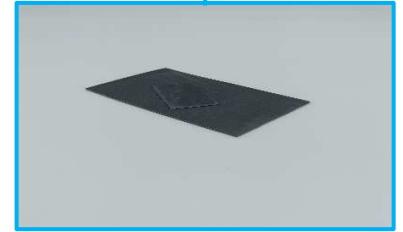


Our Thermal Foams also called Gap Pad or Gap Filler are silicone-based thermo-conductive materials that solve the problems of heat dissipation. The TEL_500_Z is a mattress specially developed for applications where a low cooling requirement is required. Indeed, it is an excellent thermal conductor of 50W/ mK, with a good thermal resistance facilitating the transfer of heat and does not have electrical insulation. We can cut according to customer plan. All our mattresses are certified UL 94 in V0.

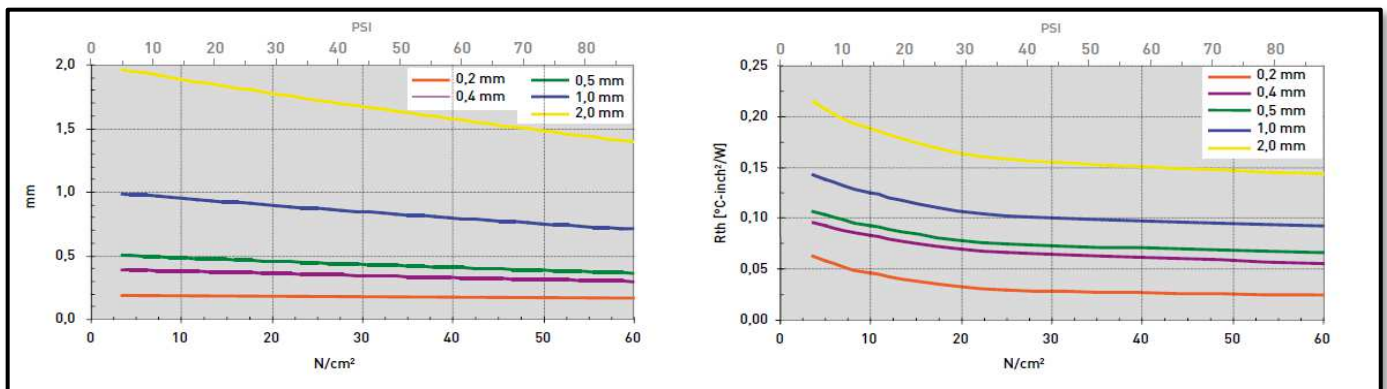


Application areas: Electronic components - Electric Vehicles, 5G, Autopilot System, Mobile Phone, AIOT, HPC (High Performance Computing), Server, IC, CPU, MOS, LED ,Mother Board, Power Supply, Heat Sink, LCD-TV, Notebook, PC, Telecom Device, Wireless Hub, DDR II Module, etc.

Technical characteristics

Features	Unit	TEL_500_Z			
Thickness	mm	0.2	0.5	1	-
Reinforcement	-	-			
Color	-	Black			
Hardness	Shore 00	75			
Size	mm	140*140			
Resistance @90 Psi	°C-inch ² /W (mm)	0.020 (0.16)	0.060 (0.33)	0.09 (0.70)	-
Resistance @30 Psi		0.027 (0.18)	0.075 (0.48)	0.11 (0.91)	-
Resistance @10 Psi		0.050 (0.19)	0.095 (0.49)	0.13 (0.97)	-
Thermal conductivity	W/mK	50			
Temperature	°C	-50 to 180			
Breakdown voltage	kV/mm	-			
Volume resistance	Ohm - cm	< 50,000			
Contante dielectric	@1MHz	-			

The TEL_500_Z is available in 0.2/0.4/0.5/1/1.5/2mm thicknesses.



Results obtained under laboratory conditions and should be considered as a guide only. AB2E has no control over its customers' hardware and many other factors, it is the user's responsibility to perform their own tests to ensure that the product meets their needs.